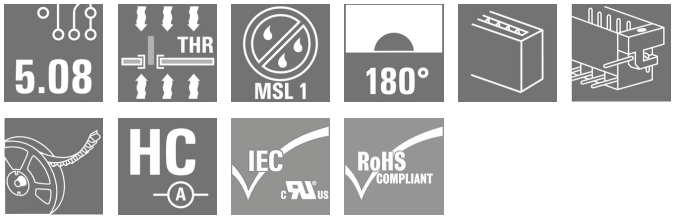
SL-SMT 5.08HC/04/180LF 3.2 AU BK RL

Weidmüller Interface GmbH & Co. KG
Klingenbergstraße 26
D-32758 Detmold
Germany

www.weidmueller.com

Product image



High-temperature-resistant pin header, packed in box or tape. On tape, with 1.5 mm solder pin, optimised for automatic assembly. 3.2 mm solder pin suitable for reflow and wave soldering. The pin headers provide space for labelling and can be coded. HC = High Current.

General ordering data

Version	PCB plug-in connector, male header, Solder flange, THT/THR solder connection, 5.08 mm, Number of poles: 4, 180°, Solder pin length (l): 3.2 mm, Gold-plated, black, Tape
Order No.	1924790000
Type	SL-SMT 5.08HC/04/180LF 3.2 AU BK RL
GTIN (EAN)	4032248590230
Qty.	250 pc(s).
Product data	IEC: 400 V / 27.5 A UL: 300 V / 18.5 A
Packaging	Tape

Creation date July 9, 2025 9:55:50 AM CEST

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Technical data

Dimensions and weights

Depth	8.5 mm	Depth (inches)	0.335 inch
Height	15.2 mm	Height (inches)	0.598 inch
Height of lowest version	12 mm	Width	30.12 mm
Width (inches)	1.186 inch	Net weight	4.013 g

System specifications

Product family	OMNIMATE Signal - series BL/SL 5.08	Type of connection	Board connection
Mounting onto the PCB	THT/THR solder connection	Pitch in mm (P)	5.08 mm
Pitch in inches (P)	0.2 "	Outgoing elbow	180°
Number of poles	4	Number of solder pins per pole	1
Solder pin length (l)	3.2 mm	Solder pin length tolerance	0 / -0.3 mm
Solder pin dimensions	d = 1.2 mm, Octagonal	Solder eyelet hole diameter (D)	1.5 mm
Solder eyelet hole diameter tolerance (D)	+ 0,1 mm	L1 in mm	15.24 mm
L1 in inches	0.6 "	Number of rows	1
Pin series quantity	1	Touch-safe protection acc. to DIN VDE 57 106	finger-safe unplugged/ back-of-hand-safe plugged
Touch-safe protection acc. to DIN VDE 0470	IP20 plugged/ IP10 unplugged	Protection degree	IP20
Volume resistance	≤5 mΩ	Plugging force/pole, max.	9 N
Pulling force/pole, max.	7 N		

Material data

Colour	black	Colour chart (similar)	RAL 9011
Insulating material group	IIIa	Comparative Tracking Index (CTI)	≥ 175
Contact material	Cu-alloy	Contact surface	Gold-plated
Layer structure of solder connection	1...3 µm Ni / 2...4 µm Sn matt	Layer structure of plug contact	1...3 µm Ni / 2...4 µm Sn / 1.7...2.3 µm Au
Storage temperature, min.	-40 °C	Storage temperature, max.	70 °C
Operating temperature, min.	-50 °C	Operating temperature, max.	100 °C
Temperature range, installation, min.	-30 °C	Temperature range, installation, max.	100 °C

Rated data acc. to IEC

tested acc. to standard	IEC 60664-1, IEC 61984	Rated current, min. number of poles (Tu=20°C)	27.5 A
Rated current, max. number of poles (Tu=20°C)	19 A	Rated current, min. number of poles (Tu=40°C)	24 A
Rated current, max. number of poles (Tu=40°C)	16.5 A	Rated voltage for surge voltage class / pollution degree II/2	400 V
Rated voltage for surge voltage class / pollution degree III/2	320 V	Rated voltage for surge voltage class / pollution degree III/3	250 V
Rated impulse voltage for surge voltage class/ pollution degree II/2	4 kV	Rated impulse voltage for surge voltage class/ pollution degree III/2	4 kV
Rated impulse voltage for surge voltage class/ contamination degree III/3	4 kV		

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Technical data

Rated data acc. to CSA

Institute (CSA)		Certificate No. (CSA)	200039-1176845
Rated voltage (Use group B / CSA)	300 V	Rated voltage (Use group D / CSA)	300 V
Rated current (Use group D / CSA)	18.5 A	Reference to approval values	Specifications are maximum values, details - see approval certificate.

Rated data acc. to UL 1059

Institute (UR)		Certificate No. (UR)	E60693
Rated voltage (Use group B / UL 1059)	300 V	Rated voltage (Use group D / UL 1059)	300 V
Rated current (Use group B / UL 1059)	18.5 A	Rated current (Use group D / UL 1059)	10 A
Reference to approval values	Specifications are maximum values, details - see approval certificate.		

Packing

ESD Level packaging	static dissipative	Packaging	Tape
VPE length	330 mm	VPE width	330 mm
VPE height	51 mm	Tape depth (T2)	17.45 mm
Tape width (W)	44 mm	Tape pocket depth (K0)	16.95 mm
Tape pocket height (A0)	8 mm	Tape pocket width (B0)	30.58 mm
Tape pocket separation (P1)	16 mm	Tape hole separation (E)	1.75 mm
Tape pocket separation (F)	20.2 mm	Tape reel diameter ⌀ (A)	330 mm
Surface resistance	Rs = 10^9 - 10^{12} Ω	Width Pick & Place Pad (W_{PPP})	9.6 mm
Length Pick & Place Pad (L_{PPP})	9.55 mm	Diameter of the withdrawal surface (ø D_{max})	8.5 mm
Protrusion 1 Pick & Place Pad ($L_{01\ (PPP)}$)	0.7 mm	Protrusion 2 Pick & Place Pad ($P_{02\ (PPP)}$)	0.4 mm

Classifications

ETIM 6.0	EC002637	ETIM 7.0	EC002637
ETIM 8.0	EC002637	ETIM 9.0	EC002637
ETIM 10.0	EC002637	ECLASS 9.0	27-44-04-02
ECLASS 9.1	27-44-04-02	ECLASS 10.0	27-44-04-02
ECLASS 11.0	27-46-02-01	ECLASS 12.0	27-46-02-01
ECLASS 13.0	27-46-02-01	ECLASS 14.0	27-46-02-01
ECLASS 15.0	27-46-02-01		

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Technical data

Approvals

Approvals	
Approvals MAMID	https://mdcop.weidmueller.com/mediadelivery/rendition/900_319226/-T1z1mm-S800/ https://mdcop.weidmueller.com/mediadelivery/rendition/900_319262/-T1z1mm-S800/
ROHS	Conform
UL File Number Search	UL Website
Certificate No. (UR)	E60693

Environmental Product Compliance

RoHS Compliance Status	Compliant without exemption
REACH SVHC	No SVHC above 0.1 wt%

Important note

IPC conformity	Conformity: The products are developed, manufactured and delivered according international recognized standards and norms and comply with the assured properties in the data sheet resp. fulfill decorative properties in accordance with IPC-A-610 "Class 2". Further claims on the products can be evaluated on request.
Notes	• Gold-plated contact surfaces on request • Rated current related to rated cross-section & min. No. of poles. • Diameter of solder eyelet D = 1.4+0.1mm • Solder eyelet diameter D = 1.5 + 0.1 mm, from 9 poles • P on drawing = pitch • Rated data refer only to the component itself. Clearance and creepage distances to other components are to be designed in accordance with the relevant application standards. • In accordance with IEC 61984, OMNIMATE-connectors are connectors without breaking capacity (COC). During designated use, connectors are not allowed to be engaged or disengaged when live or under load • Long term storage of the product with average temperature of 50 °C and maximum humidity 70%, 36 months

Downloads

Approval/Certificate/Document of Conformity	CB Certificate CB Testreport
Product Change Notification	Changeover to ESD bags for "Tape on Reel" products Umstellung auf ESD-Beutel bei „Tape on Reel" Produkten
Catalogues	Catalogues in PDF-format
Brochures	FL DRIVES EN FL DRIVES DE
White paper surface mount technology	Download Whitepaper

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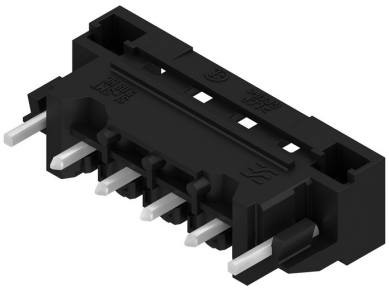
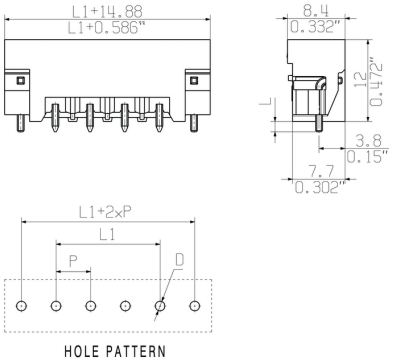
Drawings

Product image



Dimensional drawing



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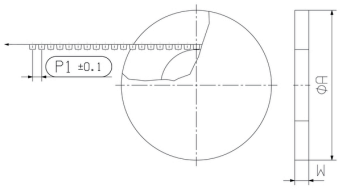
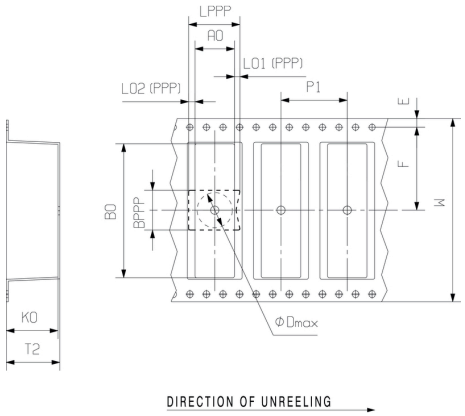
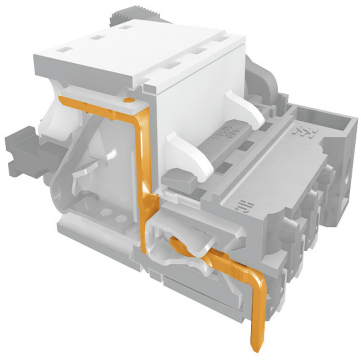


Dimensional drawing



Example of use

Product benefits



Safe power transmission
Proven properties

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Accessories

Coding elements

Only connects what is supposed to be connected: the right connection at the right place.
Coding elements and locking devices clearly assign connecting elements during the manufacturing process and operation
The coding elements and locking devices are inserted prior to assembly or during the cable assembly phase.
The Weidmüller alternative: configure online using the variant configurator to precode prior to delivery.
Incorrect assembly on the circuit board and incorrect plugging of connecting elements is no longer possible.
The advantage: no troubleshooting during manufacture and no operational errors by the user.

General ordering data

Type	BLZ/SL KO OR BX	Version	Product data	Packaging
Order No.	1573010000	PCB plug-in connector, Accessories, Coding element, orange, Number		Box
GTIN (EAN)	4008190048396	of poles: 1		
Qty.	100 pc(s).			

Type	BLZ/SL KO BK BX	Version	Product data	Packaging
Order No.	1545710000	PCB plug-in connector, Accessories, Coding element, black, Number		Box
GTIN (EAN)	4008190087142	of poles: 1		
Qty.	50 pc(s).			

Wave Solder Profile

Recommended wave solderding profiles

Weidmüller Interface GmbH & Co. KG
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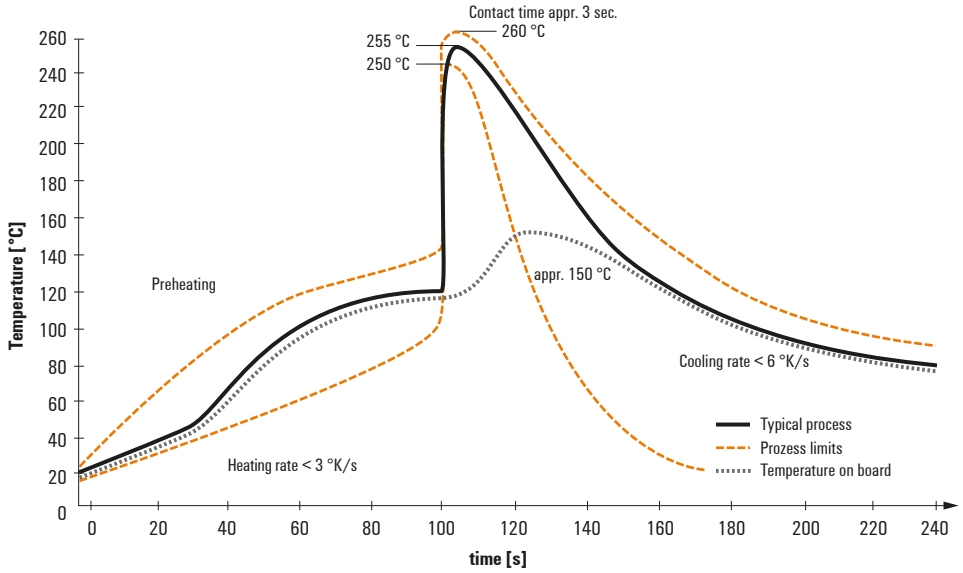
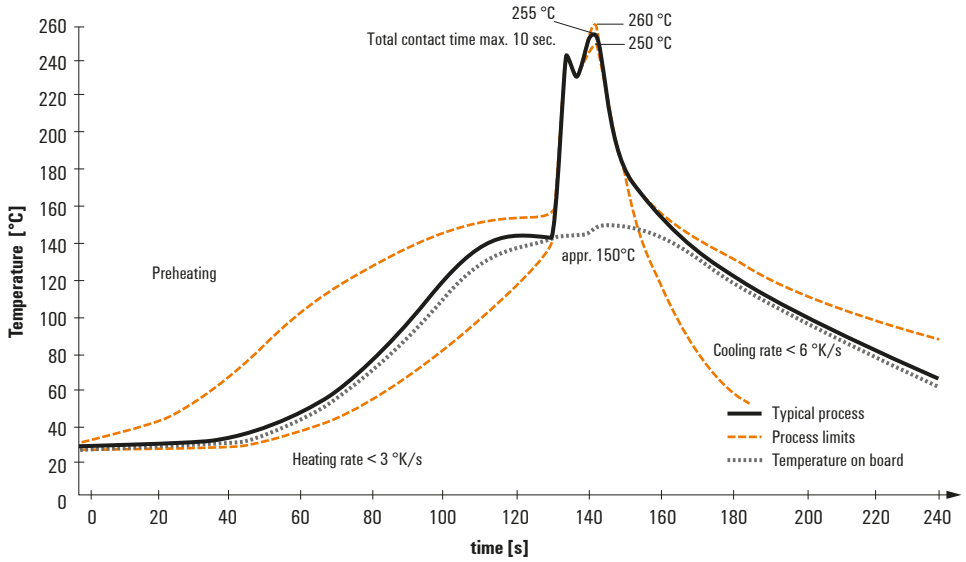
Single Wave:



Double Wave:



Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:
- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.

Reflow Solder Profile

Recommended reflow soldering profile

Weidmüller Interface GmbH & Co. KG
Klingenbergstraße 16
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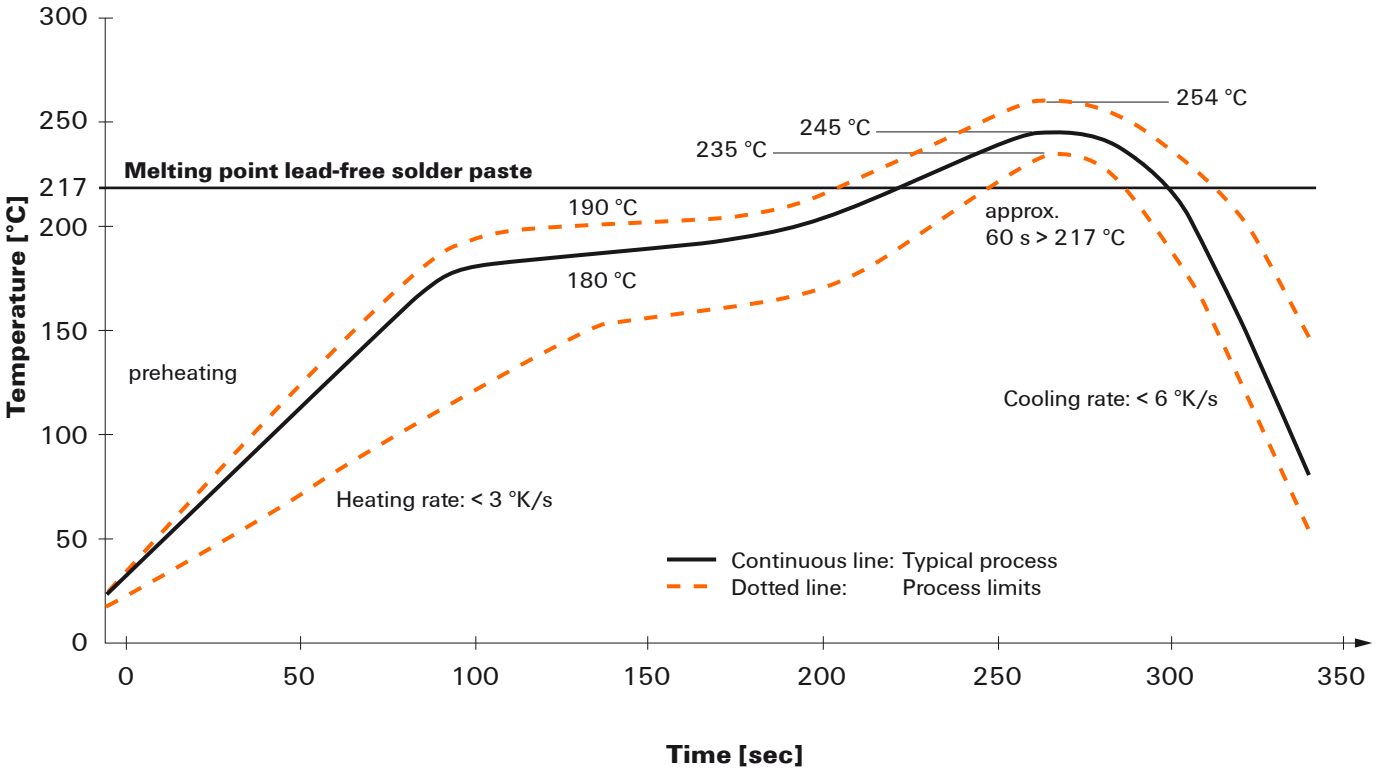

Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:
- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically ≤ +3K/s. In parallel the solder paste is ‚activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at ≥ -6K/s solder is cured. Board and components cool down while avoiding cold cracks.